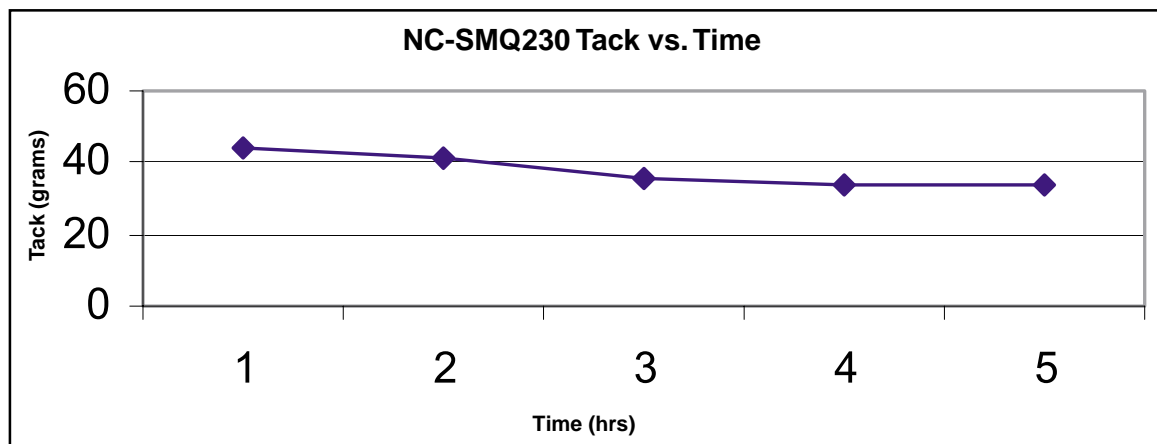




Tack vs. Time (stressed conditions)

The following test was designed to simulate the actual life of a solder paste on a stencil. Indium Corporation's Research & Development Facility tested NC-SMQ230's tack stability over time while the paste was being continuously stressed (ICA's proprietary method for stressing the paste was designed to simulate the shear caused by a squeegee blade). Tack measurements were taken every two hours over an eight-hour period with a Malcom TK-1 Tackiness Tester per IPC-TM-650. NC-SMQ230 maintained tack strength and stability for the duration of the study. This test was performed at 54% RH and 22°C.



Solder paste tack stability is an indication of minimal paste “dry-out” at room temperature, a solder paste property critical to achieving an efficient, profitable assembly process. This is especially true in high mix, low volume manufacturing facilities.

Results demonstrate NC-SMQ230's ability to maintain tack strength over an eight-hour period of continuous shearing.